

	Hits	Search Text	DBs
53	0	((resist or photoresist) near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4 or irradiat\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (thickness) same (heat or (thermal\$3 near6 treat\$4)) same (surfactant)) and (surfactant same (cationic or anionic or amphoteric)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
54	14	((resist or photoresist) near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4 or irradiat\$4)) and (resin\$4 same (water\$5soluble) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (thickness) same (heat or (thermal\$3 near6 treat\$4)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
55	0	((resist or photoresist) near36 (opening or hole or groove or recess) near39 (expos\$4 or imag\$4 or irradiat\$4)) and (((resin\$4 or resist or photoresist) near12 surfactant) same (thicken\$5 or enhanc\$4 or smooth\$6 or shrinking or coat\$4) same (thickness) same (heat or (thermal\$3 near6 treat\$4)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB